

# CD54/74HC240, CD54/74HCT240, CD74HC241, CD54/74HCT241, CD54/74HC244, CD54/74HCT244

## High-Speed CMOS Logic Octal Buffer/Line Drivers, Three-State

### Features

- HC/HCT240 Inverting
- HC/HCT241 Non-Inverting
- HC/HCT244 Non-Inverting
- Typical Propagation Delay = 8ns at  $V_{CC} = 5V$ ,  $C_L = 15pF$ ,  $T_A = 25^\circ C$  for HC240
- Three-State Outputs
- Buffered Inputs
- High-Current Bus Driver Outputs
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . .  $-55^\circ C$  to  $125^\circ C$
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The 'HC240 and 'HCT240 are inverting three-state buffers having two active-low output enables. The CD74HC241, 'HCT241, 'HC244 and 'HCT244 are non-inverting three-state buffers that differ only in that the 241 has one active-high and one active-low output enable, and the 244 has two active-low output enables. All three types have identical pinouts.

### Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC240F3A	-55 to 125	20 Ld CERDIP
CD54HC244F3A	-55 to 125	20 Ld CERDIP
CD54HCT240F3A	-55 to 125	20 Ld CERDIP
CD54HCT241F3A	-55 to 125	20 Ld CERDIP
CD54HCT244F3A	-55 to 125	20 Ld CERDIP
CD74HC240E	-55 to 125	20 Ld PDIP
CD74HC240M	-55 to 125	20 Ld SOIC
CD74HC240M96	-55 to 125	20 Ld SOIC
CD74HC241E	-55 to 125	20 Ld PDIP
CD74HC241M	-55 to 125	20 Ld SOIC
CD74HC241M96	-55 to 125	20 Ld SOIC
CD74HC244E	-55 to 125	20 Ld PDIP
CD74HC244M	-55 to 125	20 Ld SOIC
CD74HC244M96	-55 to 125	20 Ld SOIC
CD74HCT240E	-55 to 125	20 Ld PDIP
CD74HCT240M	-55 to 125	20 Ld SOIC
CD74HCT240M96	-55 to 125	20 Ld SOIC
CD74HCT240PW	-55 to 125	20 Ld TSSOP
CD74HCT240PWR	-55 to 125	20 Ld TSSOP
CD74HCT240PWT	-55 to 125	20 Ld TSSOP
CD74HCT241E	-55 to 125	20 Ld PDIP
CD74HCT241M	-55 to 125	20 Ld SOIC
CD74HCT241M96	-55 to 125	20 Ld SOIC
CD74HCT244E	-55 to 125	20 Ld PDIP
CD74HCT244M	-55 to 125	20 Ld SOIC
CD74HCT244M96	-55 to 125	20 Ld SOIC

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

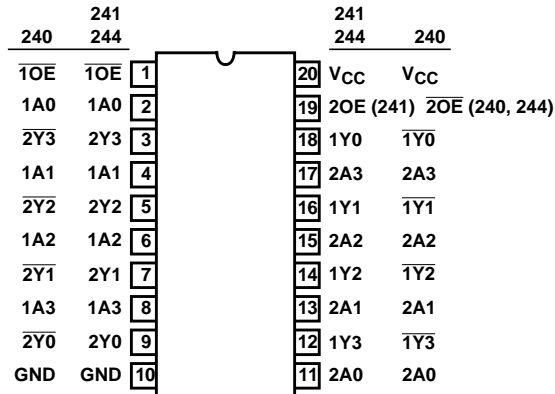
**Pinout**

CD54HC240, CD54HCT240, CD54HCT241,  
CD54HC244, CD54HCT244  
(CERDIP)

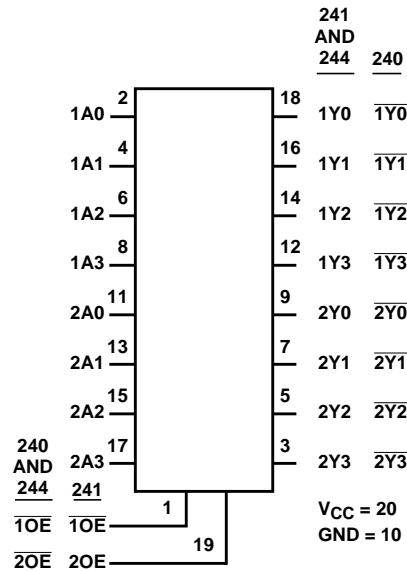
CD74HC240, CD74HC241, CD74HCT241,  
CD74HC244, CD74HCT244  
(PDIP, SOIC)

CD74HCT240,  
(PDIP, SOIC, TSSOP)

TOP VIEW



**Functional Diagram**



**Absolute Maximum Ratings**

DC Supply Voltage,  $V_{CC}$  ..... -0.5V to 7V  
 DC Input Diode Current,  $I_{IK}$   
 For  $V_I < -0.5V$  or  $V_I > V_{CC} + 0.5V$  .....  $\pm 20mA$   
 DC Output Diode Current,  $I_{OK}$   
 For  $V_O < -0.5V$  or  $V_O > V_{CC} + 0.5V$  .....  $\pm 20mA$   
 DC Drain Current, per Output,  $I_O$   
 For  $-0.5V < V_O < V_{CC} + 0.5V$  .....  $\pm 35mA$   
 DC Output Source or Sink Current per Output Pin,  $I_O$   
 For  $V_O > -0.5V$  or  $V_O < V_{CC} + 0.5V$  .....  $\pm 25mA$   
 DC  $V_{CC}$  or Ground Current,  $I_{CC}$  .....  $\pm 70mA$

**Thermal Information**

Thermal Resistance (Typical, Note 1)  $\theta_{JA}$   
 E (PDIP) Package ..... 69°C/W  
 M (SOIC) Package ..... 58°C/W  
 PW (TSSOP) Package ..... 83°C/W  
 Maximum Junction Temperature ..... 150°C  
 Maximum Storage Temperature Range ..... -65°C to 150°C  
 Maximum Lead Temperature (Soldering 10s) ..... 300°C  
 (SOIC - Lead Tips Only)

**Operating Conditions**

Temperature Range ( $T_A$ ) ..... -55°C to 125°C  
 Supply Voltage Range,  $V_{CC}$   
 HC Types ..... 2V to 6V  
 HCT Types ..... 4.5V to 5.5V  
 DC Input or Output Voltage,  $V_I, V_O$  ..... 0V to  $V_{CC}$   
 Input Rise and Fall Time  
 2V ..... 1000ns (Max)  
 4.5V ..... 500ns (Max)  
 6V ..... 400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

**DC Electrical Specifications**

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-6	4.5	3.98	-	-	3.84	-	3.7	-	V
			-7.8	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	6	4.5	-	-	0.26	-	0.33	-	0.4	V
			7.8	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$
Quiescent Device Current	$I_{CC}$	$V_{CC}$ or GND	0	6	-	-	8	-	80	-	160	$\mu A$

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Three-State Leakage Current	I <sub>OZ</sub>	V <sub>IL</sub> or V <sub>IH</sub>	-	6	-	-	±0.5	-	±0.5	-	±10	µA
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-6	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			6	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> to GND	0	5.5	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 2)	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA
Three-State Leakage Current	I <sub>OZ</sub>	V <sub>IL</sub> or V <sub>IH</sub>	-	5.5	-	-	±0.5	-	±5	-	±10	µA

NOTE:

2. For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

INPUT	UNIT LOADS
<b>HCT240</b>	
nA0-A3	1.5
$\overline{1OE}$	0.7
$\overline{2OE}$	0.7
<b>HCT241</b>	
nA0-A3	0.7
$\overline{1OE}$	0.7
2OE	1.5
<b>HCT244</b>	
nA0-A3	0.7
$\overline{1OE}$	0.7
$\overline{2OE}$	0.7

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Specifications table, e.g., 360µA max at 25°C.

**CD54/74HC240, CD54/74HCT240, CD74HC241, CD54/74HCT241, CD54/74HC244, CD54/74HCT244**

**Switching Specifications**  $C_L = 50\text{pF}$ , Input  $t_r, t_f = 6\text{ns}$

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
<b>HC TYPES</b>													
Propagation Delay Data to Outputs HC240	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	2	-	-	100	-	-	125	-	-	150	ns
			4.5	-	-	20	-	-	25	-	-	30	ns
		$C_L = 15\text{pF}$	5	-	8	-	-	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	17	-	-	21	-	-	26	ns
Data to Outputs HC241	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	2	-	-	110	-	-	140	-	-	165	ns
			4.5	-	-	22	-	-	28	-	-	33	ns
		$C_L = 15\text{pF}$	5	-	9	-	-	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	19	-	-	24	-	-	28	ns
Data to Outputs HC244	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	2	-	-	110	-	-	140	-	-	165	ns
			4.5	-	-	22	-	-	28	-	-	33	ns
		$C_L = 15\text{pF}$	5	-	9	-	-	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	19	-	-	24	-	-	28	ns
Output Enable and Disable Time	$t_{THL}, t_{TLH}$	$C_L = 50\text{pF}$	2	-	-	150	-	-	190	-	-	225	ns
			4.5	-	-	30	-	-	38	-	-	45	ns
		5	-	12	-	-	-	-	-	-	-	-	ns
		6	-	-	26	-	-	33	-	-	38	ns	
Output Transition Time	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	2	-	-	60	-	-	75	-	-	90	ns
			4.5	-	-	12	-	-	15	-	-	18	ns
			6	-	-	10	-	-	13	-	-	15	ns
Input Capacitance	$C_I$	$C_L = 50\text{pF}$	-	10	-	10	-	-	10	-	-	10	pF
Three-State Output Capacitance	$C_O$	$C_L = 50\text{pF}$	-	-	-	20	-	-	20	-	-	20	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	$C_L = 15\text{pF}$	5	-	38	-	-	-	-	-	-	-	pF
			5	-	34	-	-	-	-	-	-	-	pF
			5	-	46	-	-	-	-	-	-	-	pF
<b>HCT TYPES</b>													
Propagation Delay Data to Outputs HCT240	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	22	-	-	28	-	-	33	ns
		$C_L = 15\text{pF}$	5	-	9	-	-	-	-	-	-	-	ns
Data to Outputs HCT241	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	25	-	-	31	-	-	38	ns
		$C_L = 15\text{pF}$	5	-	10	-	-	-	-	-	-	-	ns
Data to Outputs HCT244	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	4.5	-	-	25	-	-	31	-	-	38	ns
		$C_L = 15\text{pF}$	5	-	10	-	-	-	-	-	-	-	ns

**Switching Specifications**  $C_L = 50\text{pF}$ , Input  $t_r, t_f = 6\text{ns}$  (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C			-55°C TO 125°C			UNITS
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
Output Enable and Disable Times	$t_{TLH}, t_{TLH}$	$C_L = 50\text{pF}$	4.5	-	-	30	-	-	38	-	-	45	ns
Output Transition Time	$t_{THL}, t_{TLH}$	$C_L = 50\text{pF}$	4.5	-	-	12	-	-	15	-	-	18	ns
Input Capacitance	$C_I$	$C_L = 50\text{pF}$	-	10	-	10	-	-	10	-	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$												
HCT240		-	5	-	40	-	-	-	-	-	-	-	pF
HCT241		-	5	-	38	-	-	-	-	-	-	-	pF
HCT244		-	5	-	40	-	-	-	-	-	-	-	pF

NOTES:

- $C_{PD}$  is used to determine the dynamic power consumption, per channel.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $f_o$  = Output Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

**Test Circuits and Waveforms**

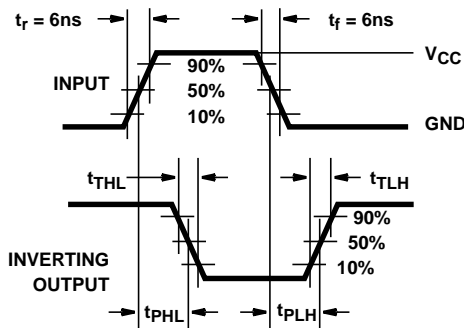


FIGURE 1. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

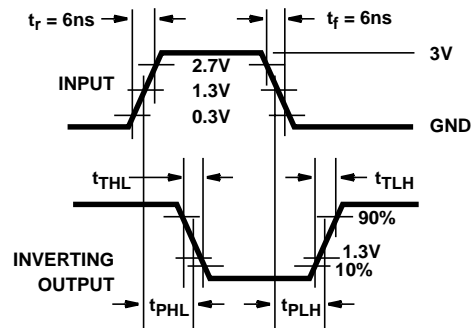


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

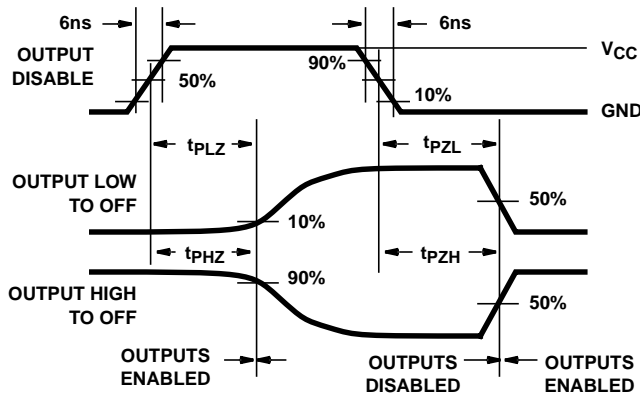


FIGURE 3. HC THREE-STATE PROPAGATION DELAY WAVEFORM

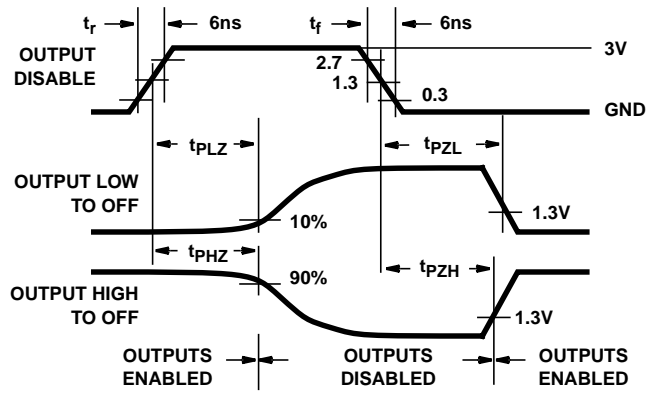
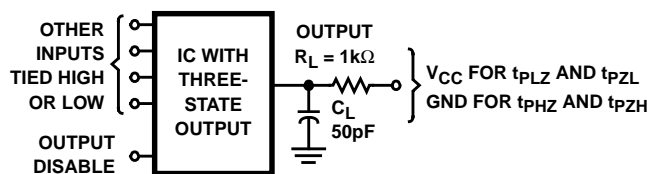


FIGURE 4. HCT THREE-STATE PROPAGATION DELAY WAVEFORM

**Test Circuits and Waveforms** (Continued)



NOTE: Open drain waveforms  $t_{PLZ}$  and  $t_{PZL}$  are the same as those for three-state shown on the left. The test circuit is Output  $R_L = 1k\Omega$  to  $V_{CC}$ ,  $C_L = 50pF$ .

**FIGURE 5. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD54HC240F3A	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407401RA CD54HC240F3A	<a href="#">Samples</a>
CD54HC244F	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54HC244F	<a href="#">Samples</a>
CD54HC244F3A	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8409601RA CD54HC244F3A	<a href="#">Samples</a>
CD54HCT240F3A	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8550501RA CD54HCT240F3A	<a href="#">Samples</a>
CD54HCT241F3A	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54HCT241F3A	<a href="#">Samples</a>
CD54HCT244F	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54HCT244F	<a href="#">Samples</a>
CD54HCT244F3A	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8513001RA CD54HCT244F3A	<a href="#">Samples</a>
CD74HC240E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC240E	<a href="#">Samples</a>
CD74HC240M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC240M	<a href="#">Samples</a>
CD74HC240M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC240M	<a href="#">Samples</a>
CD74HC240MG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC240M	<a href="#">Samples</a>
CD74HC241E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC241E	<a href="#">Samples</a>
CD74HC241EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC241E	<a href="#">Samples</a>
CD74HC241M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC241M	<a href="#">Samples</a>
CD74HC241M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC241M	<a href="#">Samples</a>
CD74HC241M96E4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC241M	<a href="#">Samples</a>
CD74HC241MG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC241M	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HC244E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC244E	<a href="#">Samples</a>
CD74HC244EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC244E	<a href="#">Samples</a>
CD74HC244M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC244M	<a href="#">Samples</a>
CD74HC244M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC244M	<a href="#">Samples</a>
CD74HC244M96E4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC244M	<a href="#">Samples</a>
CD74HC244M96G4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC244M	<a href="#">Samples</a>
CD74HC244MG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC244M	<a href="#">Samples</a>
CD74HCT240E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT240E	<a href="#">Samples</a>
CD74HCT240EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT240E	<a href="#">Samples</a>
CD74HCT240M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT240M	<a href="#">Samples</a>
CD74HCT240M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT240M	<a href="#">Samples</a>
CD74HCT240MG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT240M	<a href="#">Samples</a>
CD74HCT240PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK240	<a href="#">Samples</a>
CD74HCT240PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK240	<a href="#">Samples</a>
CD74HCT240PWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK240	<a href="#">Samples</a>
CD74HCT241E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT241E	<a href="#">Samples</a>
CD74HCT241EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT241E	<a href="#">Samples</a>
CD74HCT241M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT241M	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HCT241M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT241M	<a href="#">Samples</a>
CD74HCT241M96G4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT241M	<a href="#">Samples</a>
CD74HCT241MG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT241M	<a href="#">Samples</a>
CD74HCT244E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT244E	<a href="#">Samples</a>
CD74HCT244EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT244E	<a href="#">Samples</a>
CD74HCT244M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT244M	<a href="#">Samples</a>
CD74HCT244M96	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT244M	<a href="#">Samples</a>
CD74HCT244M96G4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT244M	<a href="#">Samples</a>
CD74HCT244ME4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT244M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF CD54HC240, CD54HC244, CD54HCT240, CD54HCT241, CD54HCT244, CD74HC240, CD74HC244, CD74HCT240, CD74HCT241, CD74HCT244 :**

● Catalog: [CD74HC240](#), [CD74HC244](#), [CD74HCT240](#), [CD74HCT241](#), [CD74HCT244](#)

● Military: [CD54HC240](#), [CD54HC244](#), [CD54HCT240](#), [CD54HCT241](#), [CD54HCT244](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC240M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CD74HC241M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CD74HC244M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CD74HCT240M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CD74HCT240PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
CD74HCT240PWT	TSSOP	PW	20	250	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
CD74HCT241M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CD74HCT244M96	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC240M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74HC241M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74HC244M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74HCT240M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74HCT240PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
CD74HCT240PWT	TSSOP	PW	20	250	367.0	367.0	38.0
CD74HCT241M96	SOIC	DW	20	2000	367.0	367.0	45.0
CD74HCT244M96	SOIC	DW	20	2000	367.0	367.0	45.0

# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

DW (R-PDSO-G20)

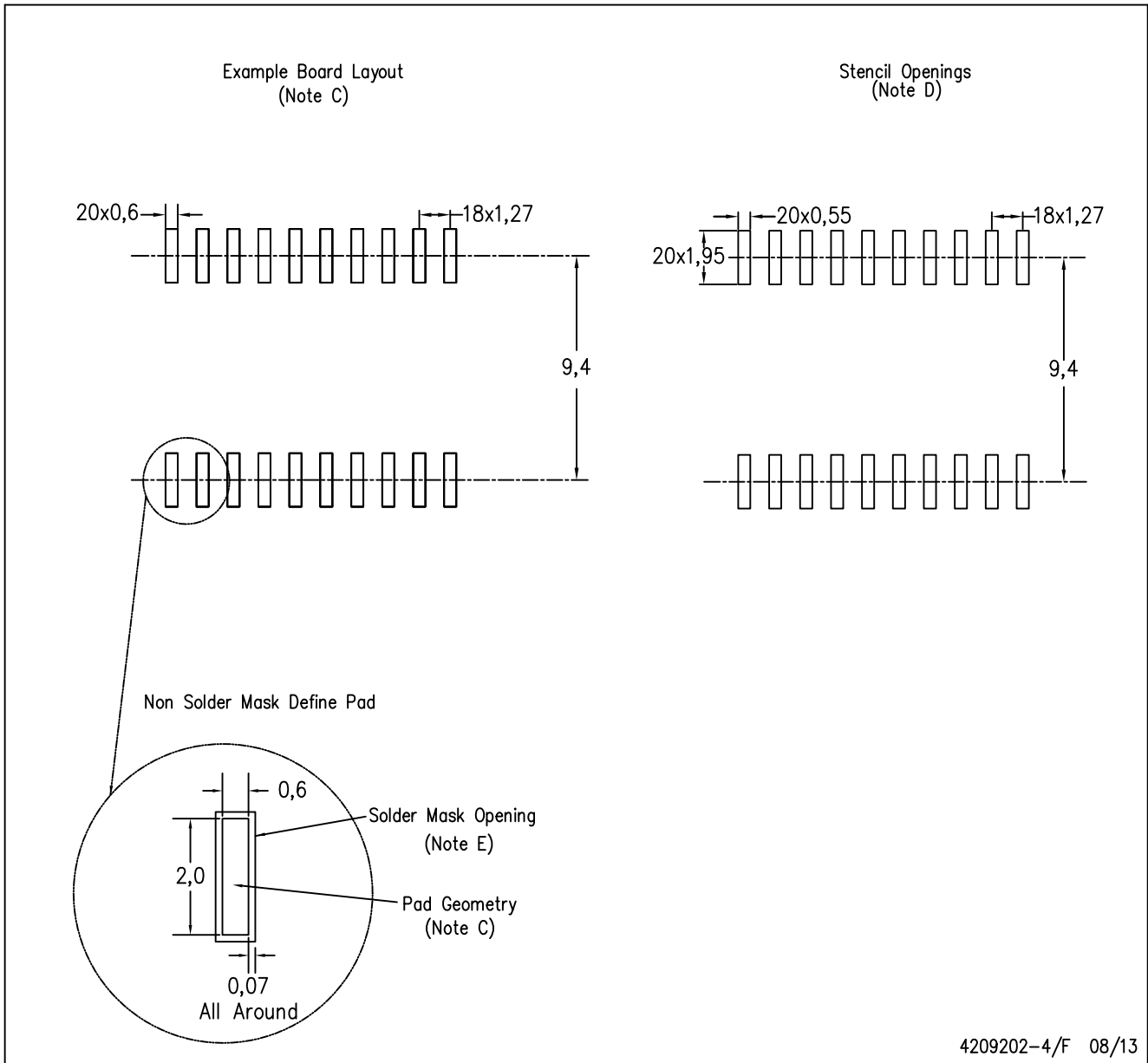
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

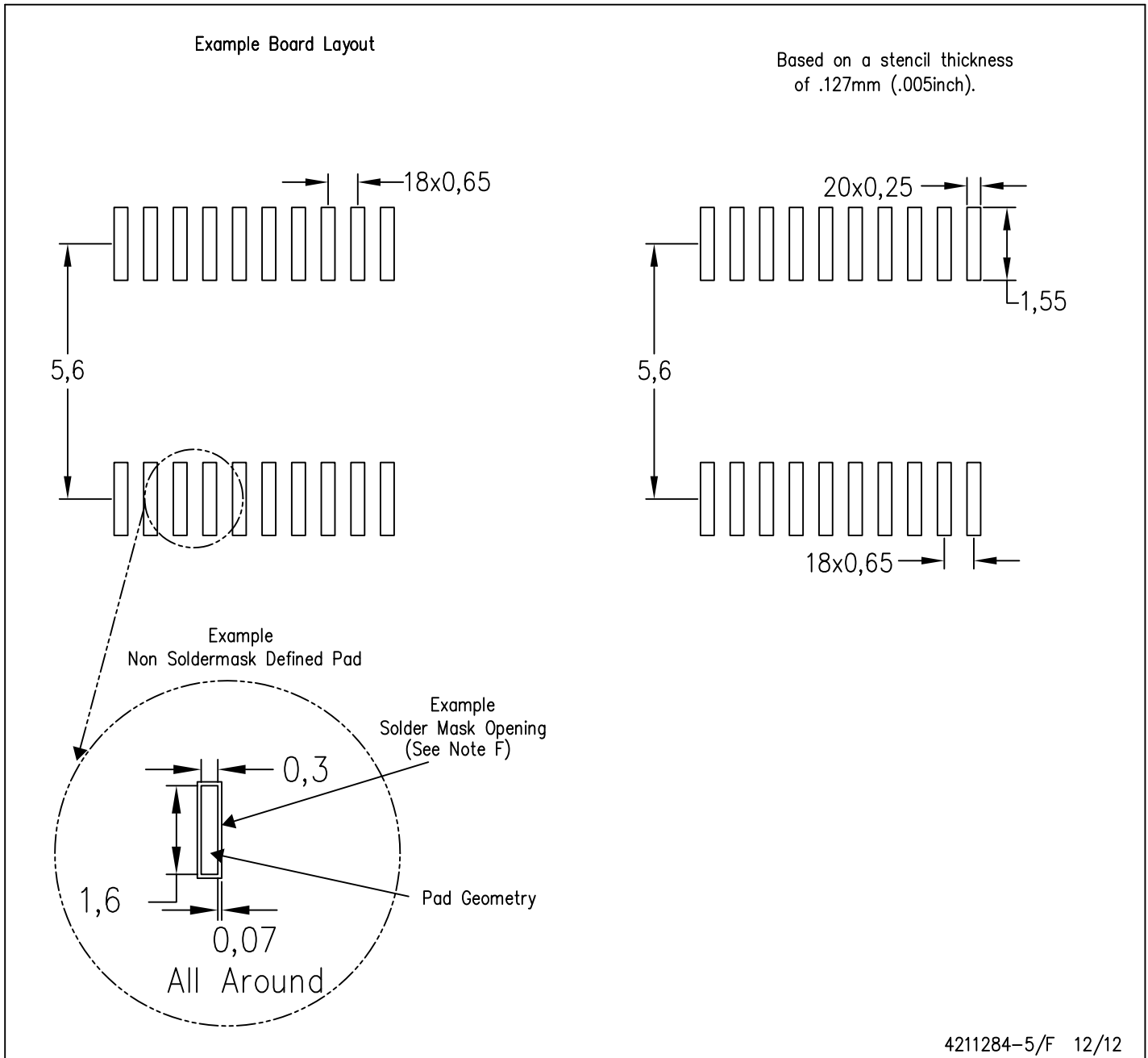


4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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